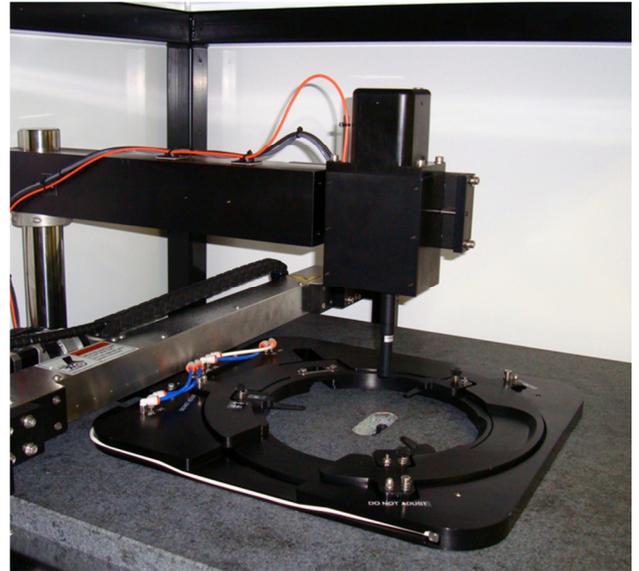


# UMS-300-WL-IR:

**Multi technology system. Stand alone stage 300mm**  
**WL confocal and IR Interferometry**



Base granite with open slot  
for 2 sensors side by side

Dual sensing technology: WL confocal + IR Interferometry  
Auto-positioning dual probes  
Automated X-Y stage on air bearing  
Granite base 31" x 32"  
Wafer size: 2" to 8" (200mm) (need 300mm stage but only 200mm wafers)  
Computer, Monitor, keyboard  
Window XP or W7 and operating software (High density scanning- low density scanning)  
Thickness, TTV, BOW, Warp, LTV (+ all local parameters)  
2D and 3D Mapping software  
Thickness range: 20um to 3mm (extended range available)  
Thickness range for IR : 20um to 800um for Si  
Up to 4mm in air

Include one wafer fixture (3 points hold)

Options:

Additional wafer holder

Open Chuck wafer holder

HISCAN software

Edge profile

Roughness

Surface structures

Includes : Mountain software

Chaining software option